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(54) Title: MOULD HALF AND MOULD METHOD FOR TRANSFER MOULDING ENCAPSULATING ELECTRONIC COMPONENTS MOUNTED ON A CARRIER INCLUDING A DUAL SUPPORT SURFACE AND A METHOD FOR USING SUCH

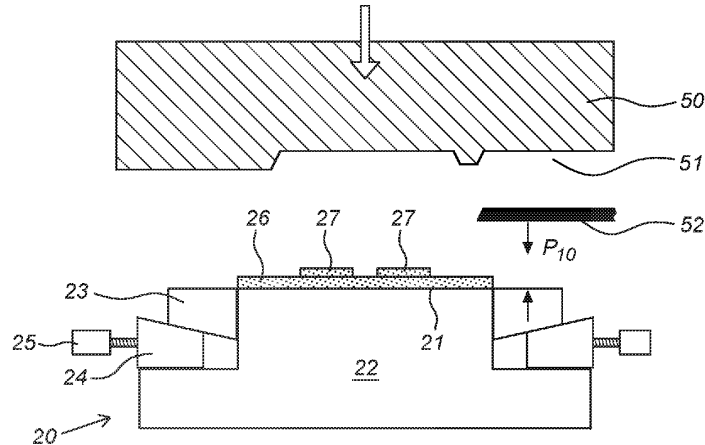


Fig. 5

(57) Abstract: The present invention relates to a mould half for a mould for transfer moulding encapsulating electronic components mounted on a carrier, wherein the mould part to support the carrier has a contact surface that comprises a primary carrier support surface and a the primary carrier support surface surrounding secondary surface, which surrounding secondary surface is supported by a drive for height adjustment of the secondary surface relative to the height of the primary carrier support surface. Such mould half may be used for transfer moulding of electronic components while relatively easy providing a levelled support for the carrier and compensating for any thickness variations in the carrier. The invention also provides a mould with at least two mould parts and a method for transfer moulding encapsulating electronic components mounted on a carrier using such a mould.

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